



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	13-11-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H742ZIT6	2A1A*450XXV	A	9991	13-11-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	1302.58	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20	144	L bend	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2A1A*450XXV				5999999.0	1000001.6
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	15.101	mg	Supplier	die	Silicon (Si)	7440-21-3		14.359	mg	950864	11023
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5827	68
				Supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	18277	212
				Supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	66	1
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2980	35
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	530	6
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	66	1
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	21389	248
				Supplier	Leadframe	Copper (Cu)	7440-50-8		315.975	mg	957500	242576
				Supplier	Leadframe	Nickel (Ni)	7440-02-0		9.834	mg	29800	7550
Leadframe (C7025 + Ag)	Copper & its alloys	330.000	mg	Supplier	Leadframe	Silicon (Si)	7440-21-3		2.145	mg	6500	1647
				Supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.495	mg	1500	380
				Supplier	Leadframe	Silver (Ag)	7440-22-4		1.551	mg	4700	1191
				Supplier	Glue or tape	Silver (Ag)	7440-22-4		3.271	mg	755000	2511
				Supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.108	mg	25000	83
Glue Epoxy (EN-4900G)	Precious metals	4.333	mg	Supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.368	mg	85000	283
				Supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.238	mg	55000	183
				Supplier	Glue or tape	Butadiene copolymer	Proprietary		0.043	mg	10000	33
				Supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.238	mg	55000	183
				Supplier	Glue or tape	Peroxy Ketals	Proprietary		0.022	mg	5000	17
				Supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.022	mg	5000	17
				Supplier	Glue or tape	Methacrylate multialkoxy-substitutedalkyl ester	Proprietary		0.022	mg	5000	17
				Supplier	Bonding wire	Copper (Cu)	7440-50-8		1.593	mg	965500	1223
				Supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.051	mg	31000	39
				Supplier	Bonding wire	Gold (Au)	7440-57-5		0.006	mg	3500	4
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	940.000	mg	Supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'	85954-11-6		37.600	mg	40000	28866
				Supplier	Molding Compound	Epoxy resin	Proprietary		18.800	mg	20000	14433
				Supplier	Molding Compound	Phenol Resin	Proprietary		70.500	mg	75000	54123
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		666.930	mg	709500	512006
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		141.000	mg	150000	108246
External Plating (Sn)	M-011 Other inorganic materials	11.500	mg	Supplier	Molding Compound	Carbon black	1333-86-4		5.170	mg	5500	3969
				Supplier	Matte Sn	Tin (Sn)	7440-31-5		11.499	mg	999900	8828
				Supplier	Matte Sn	Impurities	-		0.001	mg	100	1